ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES®	© Co	terial Compo byright 2005. IPC, Bannoc ternational and Pan-Ameri	kburn, Illinois	. All rights reserve	ION with lower	level	parts, the	declaratio	on encor		er level materia	als for which	the item is an assembly the manufacturer has is declaration.
IPC-1752-1 v1.02 <b>1752-1</b>	IPC Web Site for Information on IPC-1752 Standard http://www.ipc.org/IPC-175x				rd		orm Type * Declaration Class * Class 4 - RoHS Yes/No, JIG Format Substances, Mfg Info						es, Mfg Info
Supplier Information													
Company Name * Anaren Microwave, Inc.	Company Unique ID		Unique ID Authority			Response Date * 2014-02-27			Response Doc	ument ID			
Contact Name * Lakshmi Achutha				Phone - Cont +1 315-432-8				Duplicate		e Contact -> Authorized Representative			
Authorized Representative * Lakshmi Achutha		Title - Representative	- Representative Phone - Representative +1 315-432-8909			Email - Representative * lachutha@anaren.com				Supplier Comn	nents or URL f	or Additiona	I Information
Requester Item Number		Mfr Item Number	Mfr Item Name			Effecti	Effective Date Version Man		Manufa	cturing Site	Weight	UOM	Unit Type
X3DC		X3DC23P1S		Doherty Combiner		2014-	02-27	D	East S	yracuse	0.101	g	Each
Alternate Recommend	ation							Alternate	e Item Co	mments			
Manufacturing Process Information													
Terminal Plating / Grid Array	Materi	al	Terminal B	ase Alloy	J-STD-020 MSL R	ating	Peak Proc	ess Body	/ Temper	ature Max Time	at Peak Tempe	rature Numb	er of Reflow Cycles
Tin (Sn) - immersion CU Allo   Comments Cu Allo			CU Alloy	,	1				<b>260</b> C		<b>30</b> seco	onds 3	

Save the fields in this form to a fileExport DataImport fields from a file into this formImport Data	Clear all of the fields on this form Reset Form Lock the fields on this form to prevent changes Lock Supplier Fields								
RoHS Material Composition Declaration	Declaration Type * Simplified								
RoHS Directive     RoHS Definition:     Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB),       2002/95/EC     Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium									
Supplier certifies that it gathered the information it provides in this form concerning RoHS restrictive substances using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others in completing their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.									
RoHS Declaration * 1 - Item(s) does not contain RoHS restricted substances per the definition above	Supplier Accepted								
<b>Exemptions:</b> If the declared item does not contain RoHS restricted substances per the definition at above and checkboxes will appear below. Check all applicable exemptions.	ove except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration								
1. Mercury in compact fluorescent lamps not exceeding 5 mg per lamp.	7c. Lead in electronic ceramic parts (e.g. piezoelectronic devices).								
2a. Mercury in straight fluorescent lamps for general purposes not exceeding 10 mg. in halophosphate lamps	8. Cadmium and its compounds in electrical contacts and cadmium plating except for applications banned under Directive 91/338/EEC amending Directive 76/769/EEC relating to restrictions on the marketing and use of certain dangerous substances and preparations piezoelectronic devices).								
2b. Mercury in straight fluorescent lamps for general purposes not exceeding 5 mg. in triphosphate lamps with a normal lifetime	<ol><li>Hexavalent chromium as an anti-corrosion of the carbon steel cooling system in absorption refrigerators</li></ol>								
2c. Mercury in straight fluorescent lamps for general purposes not exceeding 8 mg. in triphosphate lamps with long lifetime	10a. Deca BDE in polymeric applications								
3. Mercury in straight fluorescent lamps for special purposes.	10b. Lead in lead/bronze bearing shells and bushes								
4. Mercury in other lamps not specifically mentioned in this list.	11. Lead used in compliant pin connector systems.								
5. Lead in glass of cathode ray tubes, electronic components and fluorescent tubes.	12. Lead as a coating material for a thermal conduction module c-ring.								
6a. Lead as an alloying element in steel containing up to 0.35% lead by weight.	13a. Lead in optical and filter glass.								
6b. Lead as an alloying element in aluminum containing up to 0.4% lead by weight.	13b. Cadmium in optical and filter glass.								
6c. Lead as an alloying element in copper containing up to 4% lead by weight.	14. Lead in solders consisting of more than two elements for the connection between the pins and the package of microprocessors with a lead content of more than 80% and less than 85% by weight .								
7a. Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).	15. Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages.								
7b. Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signalling, transmission as well as network management for telecommunications.									
Declaration Signature	eestedii on the Oundian Acceptance daan dawn. This will display the simplifying an a Dirit ii a								
<b>Instructions:</b> Complete all of the required fields on all pages of this form. Select the "Ac the declaration (if required by the Requester) and click on Submit Form to have the form ret	cepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign urned to the Requester.								
Supplier Digital Signature									

## Joint Industry Guide (JIG) Material Composition Declaration for Electronic Products

Instructions: Declare whether the item substances exceed the threshold levels shown in the table and report accordingly. Where threshold levels include the words "intentionally added", substances must be declared if they are added intentionally, regardless of threshold level. For each RoHS substance, identified with dual asterisks (\*\*), report the worst case PPM at the homogeneous material level and optionally the total weight of the substance in the item. For all remaining (non-RoHS) JIG A & B substances, and any additional substances, report the total weight and optionally the PPM at the part level for each item.

					JIG A autofill - No		JIG B	autofill - No		All autofill -	No
JIG	Category Name	Threshold Level	Above Threshold Level?	If yes, enter total wei worse case PP					on of Use		
Level	As defined in the Joint Industry Guide	Intentionally added or PPM	Yes/No	Weight	P	PM					
А	Asbestos	Intentionally Added	No		mg						
Α	Certain Azo colorants	Intentionally Added	No		mg						
A	Cadmium/Cadmium Compounds **	75 PPM or Intentionally Added	No		mg						
A	Hexavalent Chromium/Hexavalent Chromium Compounds **	1000 PPM or Intentionally Added	No	mg							
Α	Lead/Lead Compounds **	1000 PPM or Intentionally Added	No	mg							
А	Lead/Lead Compounds - PVC Cables and Wires Only **	300 PPM	No		mg						
А	Mercury/Mercury Compounds **	1000 PPM or Intentionally Added	No		mg						
Α	Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.)	Intentionally Added	No		mg						
Α	Ozone Depleting Substances - Class II (HCFCs)	1000 PPM	No		mg						
A	Polybrominated Biphenyls (PBBs) **	1000 PPM or Intentionally Added	No		mg						
Α	Polybrominated Diphenylethers (PBDEs) **	1000 PPM or Intentionally Added	No		mg						
A	Polychlorinated Biphenyls (PCBs)	Intentionally Added	No		mg						
А	Polychlorinated Naphthalenes ( > 3 chlorine atoms)	Intentionally Added	No		mg						
A	Radioactive Substances	Intentionally Added	No		mg						
A	Certain Shortchain Chlorinated Paraffins	Intentionally Added	No		mg						
Α	Tributyl Tin (TBT) and Triphenyl Tin (TPT)	Intentionally Added	No		mg						
Α	Tributyl Tin Oxide (TBTO)	Intentionally Added	No		mg						
В	Antimony/Antimony Compounds	1000 PPM	No		mg						
В	Arsenic/Arsenic Compounds	1000 PPM	No		mg						
В	Beryllium/Beryllium Compounds	1000 PPM	No		mg						
В	Bismuth/Bismuth Compounds	1000 PPM	No		mg						
В	Brominated Flame Retardants (other than PBBs or PBDEs)	1000 PPM	No		mg						
В	Nickel (external applications only)	1000 PPM	No		mg						
В	Certain Phthalates	1000 PPM	No		mg						
В	Selenium/Selenium Compounds	1000 PPM	No		mg						
В	Polyvinyl Chloride (PVC)	1000 PPM	No		mg						

## **OTHER Material Composition Declaration**

**Requester Instructions:** The requester can optionally include additional substances that must be declared for the item on this form. This is in addition to JIG Level A and JIG Level B substances. The requester should enter additional substances as well as the threshold levels that specify the substance at the item level.

Supplier Instructions: Explicitly declare whether the item exceed the threshold level by selecting Yes or No. If the maximum concentration of any substance exceeds the threshold levels defined by the requester, then the substance content must be reported in total weight and/or worst case PPM, along with a description of material use.

JIG	Category Name	Threshold Level
Other	As defined by the Requester	Defined by the Requester
+ -		
Add	d Other Material Composition to JIG Tab	